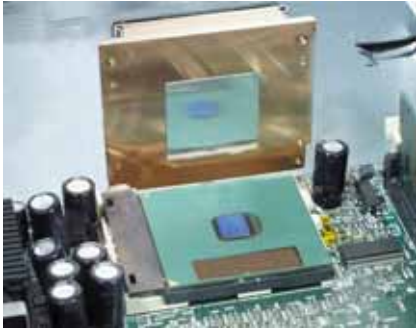


# Hi-Flow® 225UF

Unsupported, Thermally Conductive Phase Change Material

## Features and Benefits

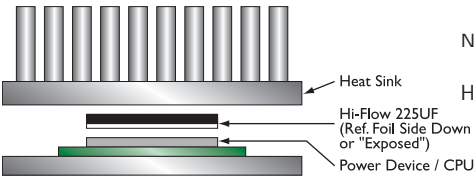
- Thermal impedance: 0.08°C-in²/W (@25 psi)
- Reworkable
- Easy release from CPU
- Easy to handle / assemble



Bergquist's reworkable Hi-Flow 225UF thermal interface material provides a low thermal resistance path between hot components such as high-performance processors and heat sinks.

Hi-Flow 225UF consists of a 55°C phase change compound bonded to one side of a conformable aluminum foil. This phase change material is easily applied to a nominal 45°C heat sink and securely conforms to many mounting surfaces. The compliant foil allows for easy release from the CPU/socket assembly, leaving the surface clean and residue-free. Hi-Flow 225UF is supplied in kiss-cut form with a carrier liner protecting the phase change material from contaminants.

Above the 55°C phase change temperature, Hi-Flow 225UF wets-out the heat sink interface and flows to produce exceptional thermal performance. Hi-Flow 225UF's thixotropic design requires pressure of the assembly to cause displacement and/or flow.



TYPICAL PROPERTIES OF HI-FLOW 225UF						
PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD			
Color	Black	Black	Visual			
Reinforcement Carrier	Aluminum	Aluminum	—			
Thickness (inch) / (mm)	0.0045	0.114	ASTM D374			
Carrier Thickness (inch) / (mm)	0.001	0.025	ASTM D374			
Continuous Use Temp (°F) / (°C)	248	120	—			
Phase Change Temp (°F) / (°C)	131	55	ASTM D3418			
THERMAL						
Thermal Conductivity (W/m-K) (1)	1.0	1.0	ASTM D5470			
THERMAL PERFORMANCE vs PRESSURE						
	Pressure (psi)	10	25	50	100	200
TO-220 Thermal Performance (°C/W)		0.70	0.58	0.52	0.43	0.37
Thermal Impedance (°C-in²/W) (2)		0.10	0.08	0.07	0.06	0.05

1) This is the measured thermal conductivity of the Hi-Flow coating. It represents one conducting layer in a three-layer laminate. The Hi-Flow coatings are phase change compounds. These layers will respond to heat and pressure induced stresses. The overall conductivity of the material in post-phase change, thin film products is highly dependent upon the heat and pressure applied. This characteristic is not accounted for in ASTM D5470. Please contact Bergquist Product Management if additional specifications are required.  
 2) The ASTM D5470 test fixture was used and the test sample was conditioned at 70°C prior to test. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

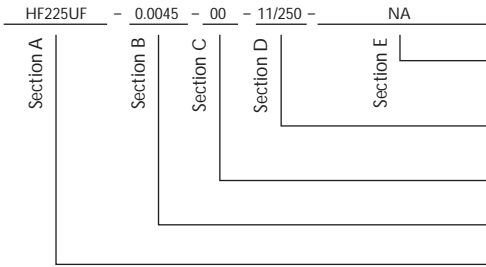
## Typical Applications Include:

- Spring / clip mounted:
  - Digital / high power CPU's
  - Power modules

## Configurations Available:

- Sheet form, kiss-cut or bulk
  - Preferred form: squares / rectangles
- Singulated die-cut parts
  - Preferred form: squares / rectangles
- Bulk roll form

## Building a Part Number



## Standard Options

◀ example  
 NA = Selected standard option. If not selecting a standard option, insert company name, drawing number, and revision level.  
 1112 = 11" x 12" sheets, 11/250 = 11" x 250' rolls, or 00 = custom configuration  
 00 = No adhesive  
 Standard thicknesses available: 0.0045"  
 HF225UF = Hi-Flow 225UF Phase Change Material

Note: To build a part number, visit our website at [www.bergquistcompany.com](http://www.bergquistcompany.com).

Hi-Flow®: U.S. Patent 6,197,859 and others



[www.bergquistcompany.com](http://www.bergquistcompany.com)

The Bergquist Company - North American Headquarters  
 18930 West 78th Street  
 Chanhassen, MN 55317  
 Phone: 800-347-4572  
 Fax: 952-835-0430

The Bergquist Company - Europe  
 Bramenberg 9a, 3755 BT Eemnes  
 Netherlands  
 Phone: 31-35-5380684  
 Fax: 31-35-5380295

The Bergquist Company - China  
 Rm. 7C, Aibe Mansion  
 No. 629 Ling Ling Road  
 Shanghai, China 200030  
 Ph: 86-21-6464-2206  
 Fax: 86-21-6464-2209

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